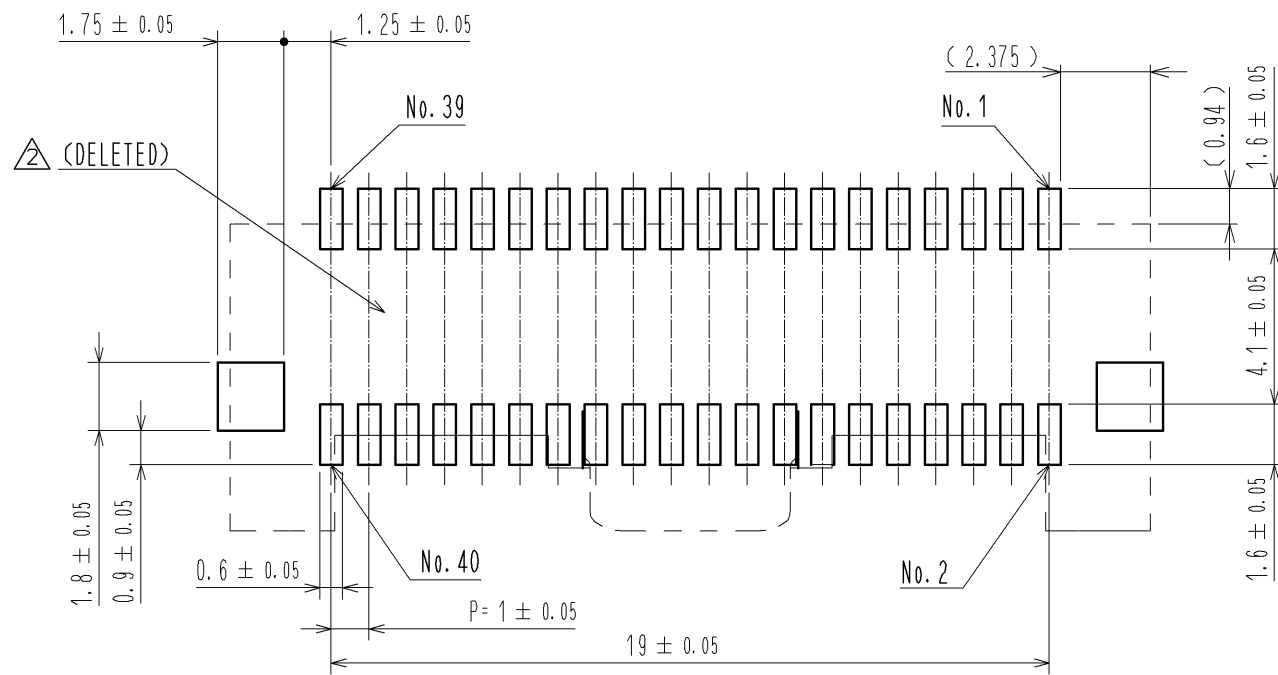


NOTE 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX  
 2. (DELETED)  
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MONUTED TO FPC.

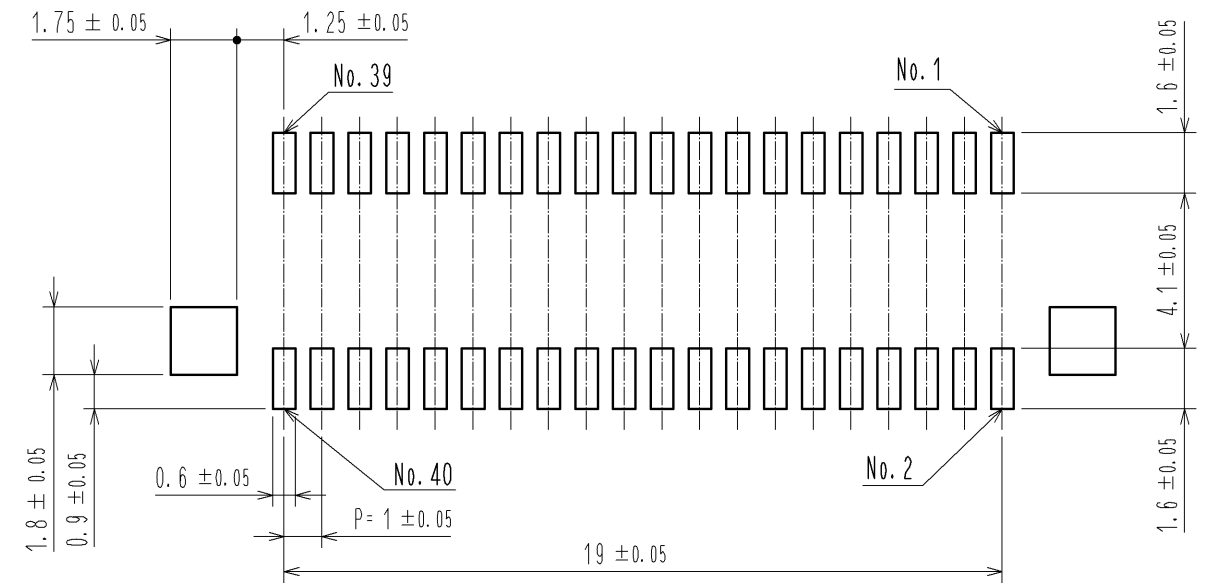
3	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	8	PS	REEL, BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	7	POLYESTER	CLEAR
1	LCP	BLACK, UL94V-0	6	PS	CLEAR
			5	STAINLESS STEEL	—
			4	BRASS	CONTACT AREA : Sn PLATING 1 μm MIN UNDER PLATING : Ni PLATING 0.5 μm MIN
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS mm		SCALE 5 : 1	COUNT 2	DESCRIPTION OF REVISIONS DIS-H-008701	
DESIGNED MI. SAKIMURA		CHECKED TS. KUMAZAWA		DATE 14. 04. 22	
APPROVED : KI. AKIYAMA 10. 12. 13		DRAWING NO. EDC3-330959-01			
CHECED : OM. MIYAMOTO 10. 12. 13		PART NO. DF50-40DP-1H(51)			
DESIGNED : TT. OHSAKO 10. 12. 10		CODE NO. CL665-0014-0-51			
DRAWN : TT. OHSAKO 10. 12. 10				1/3	

RECOMMENDED PCB LAYOUT  
(MOUNTING SURFACE SIDE) (FREE)

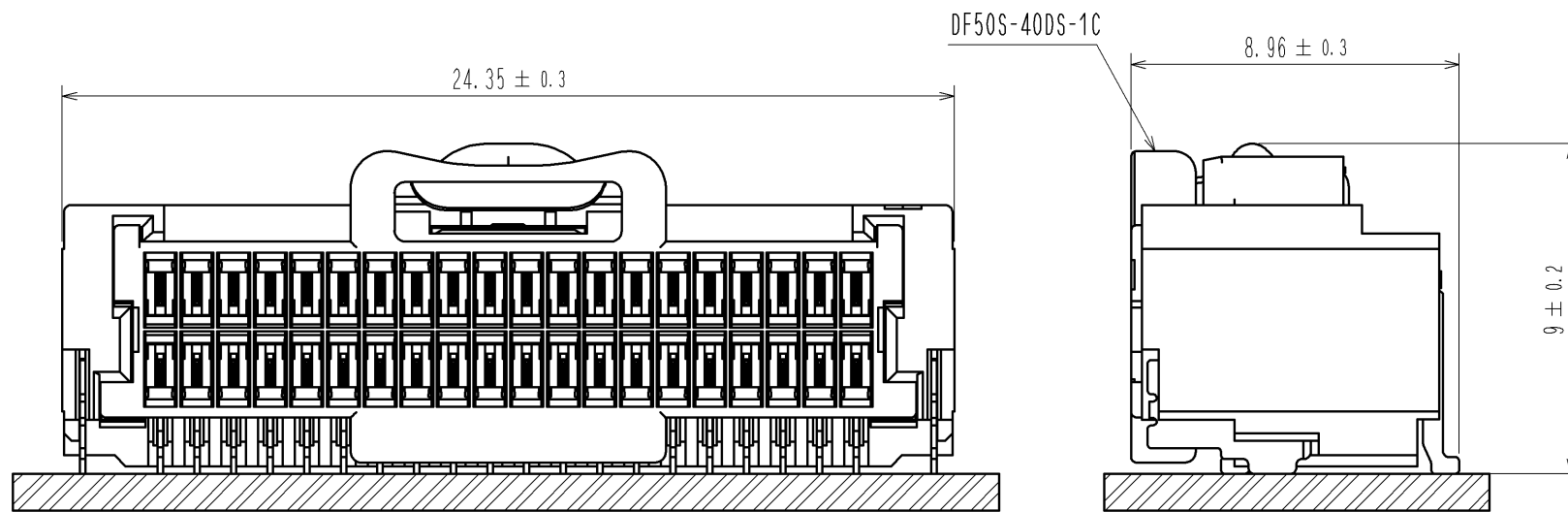


RECOMMENDED METAL MASK (FREE)

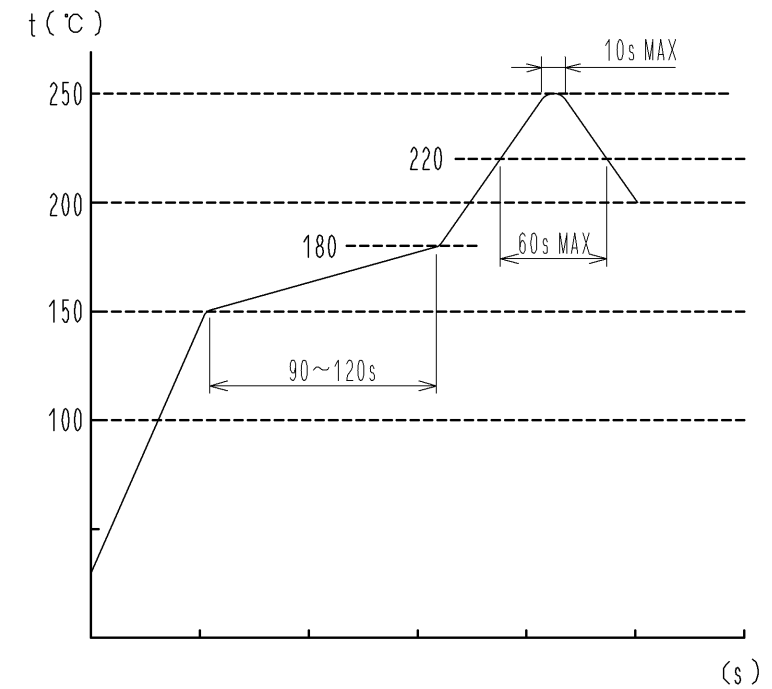
THICKNESS : 0.1mm  
OPEN AREA RATIO:100%



MATING FIGURE (5 : 1)



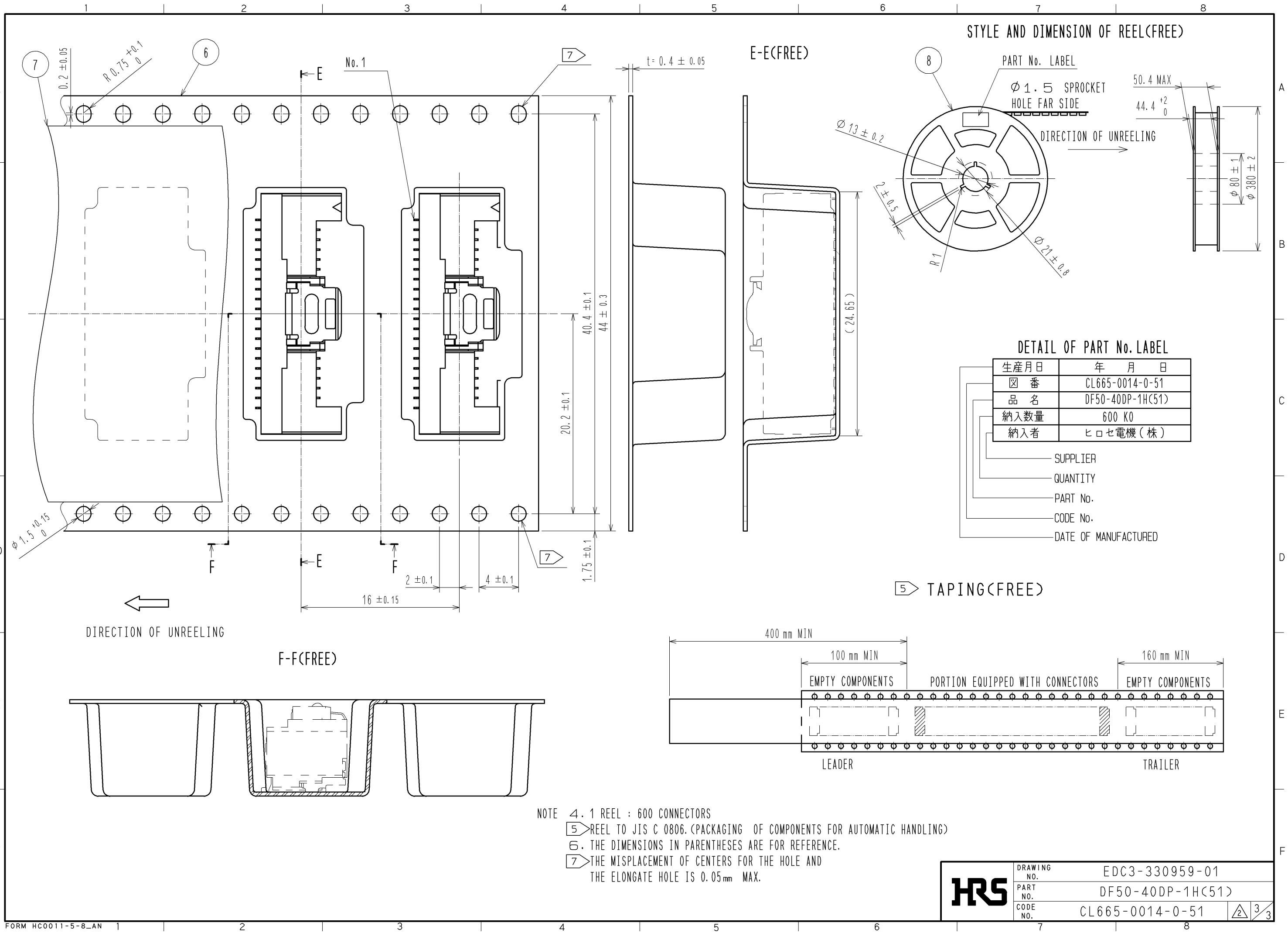
REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES 2 CYCLES MAX.  
THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.

ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE,  
PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT  
THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF  
MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION.  
TEMPERATURE IS MEASURED AT CONTACT LEAD.

<b>HRS</b>	DRAWING NO.	EDC3-330959-01
	PART NO.	DF50-40DP-1H(51)
	CODE NO.	CL665-0014-0-51
		2/3



<b>HRS</b>	DRAWING NO.	EDC3-330959-01
	PART NO.	DF50-40DP-1H(51)
	CODE NO.	CL665-0014-0-51
		3/3